Please REPLACE the paragraph beginning at page 15, line 23, as follows:

KZ

In this way, according to the present invention, the power consumed in the address drive IC (capacitive-load driving circuit) 3 can be reduced. That is, though the power consumption as a whole remains the same, a portion of the power that would have been consumed in the address drive IC 3 in the prior art is consumed by the power distributing means 2; this construction serves to simplify the heat sinking structure of the address drive IC 3, and achieves a reduction in circuit cost.

Please REPLACE the paragraph beginning at page 16, line 18, as follows:



Figure 4 is a block diagram showing a first embodiment of the capacitive-load driving circuit according to the present invention. In Figure 4, reference numeral 1 is a driving power supply source, 21 is a power distributing means, or circuit, 3 is an address drive IC, 4 is a reference potential point (ground point), 5 is a load capacitor, 6 and 7 are driving devices, 8 and 9 are a power supply terminal and a reference potential terminal (ground terminal), respectively, of the address drive IC, and 10 is an output terminal of the address drive IC.

Please REPLACE the paragraph beginning at page 16, line 29, as follows:



As shown in Figure 4, in the first embodiment, the power distributing means, or circuit, 21 is inserted between the driving power supply source 1 and the high-level voltage supply terminal 8 of the address drive IC 3; this power distributing means is constructed as a resistive impedance (resistive element) 21 whose value is higher than about one-tenth of the resistive impedance that the driving device 6 provides at the time of conduction (the resistive component of the conducting impedance). According to the first embodiment, the power consumption of the driving circuit 3 can be reduced by distributing to the resistive element 21 about one-tenth or more of the power consumed in the driving device 6 during load driving.

Please REPLACE the paragraph beginning at page 37, line 20, as follows:



As shown in Figure 27, the 17th embodiment, the present invention is applied to the address drive IC 3 for driving, for example, the number, d, address lines (A1 to Ad) in a plasma